

# **HVD365**

# Variable Capacitance Diode for VCO

REJ03G0501-0300 Rev.3.00 Jan 24, 2006

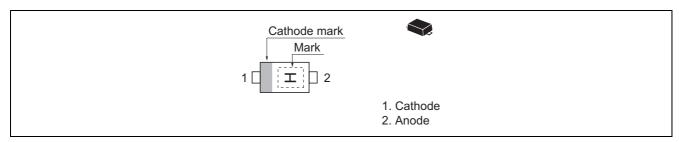
#### **Features**

- High capacitance ratio and good C-V linearity.
- Super small Flat Lead Package (SFP) is suitable for surface mount design.

# **Ordering Information**

Type No.	Laser Mark	Package Name	Package Code	
HVD365	Н	SFP	PUSF0002ZB-A	

# **Pin Arrangement**



# **Absolute Maximum Ratings**

 $(Ta = 25^{\circ}C)$ 

Item	Symbol	Value	Unit
Reverse voltage	V <sub>R</sub>	15	V
Junction temperature	Tj	125	°C
Storage temperature	Tstg	-55 to +125	°C

### **Electrical Characteristics**

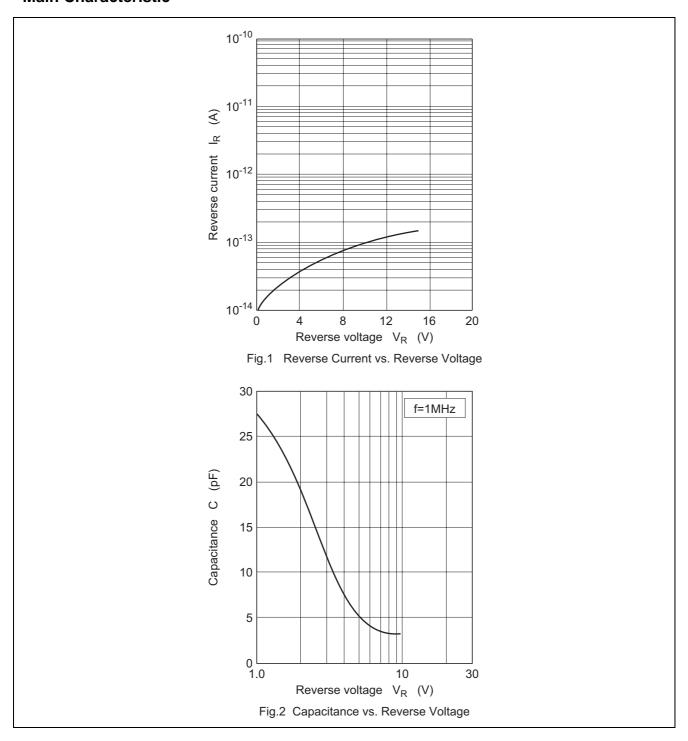
 $(Ta = 25^{\circ}C)$ 

Item	Symbol	Min	Тур	Max	Unit	Test Condition
Reverse current	I <sub>R1</sub>	_	_	10	nA	V <sub>R</sub> =10 V
	I <sub>R2</sub>	_	_	100		V <sub>R</sub> = 10 V, Ta = 60°C
Capacitance	C <sub>1</sub>	27.05	_	28.55	pF	V <sub>R</sub> = 1 V, f = 1 MHz
	C <sub>4</sub>	6.05	_	7.55		V <sub>R</sub> = 4 V, f = 1 MHz
Capacitance ratio	n	3.00	_	_	_	C <sub>1</sub> / C <sub>4</sub>
Series resistance	r <sub>S</sub>	_	_	1.50	Ω	V <sub>R</sub> = 4 V, f = 100 MHz
ESD-Capability *1	_	200	_	_	V	$C = 200 \text{ pF}$ , $R = 0 \Omega$ , Both forward
						and reverse direction 1 pulse.

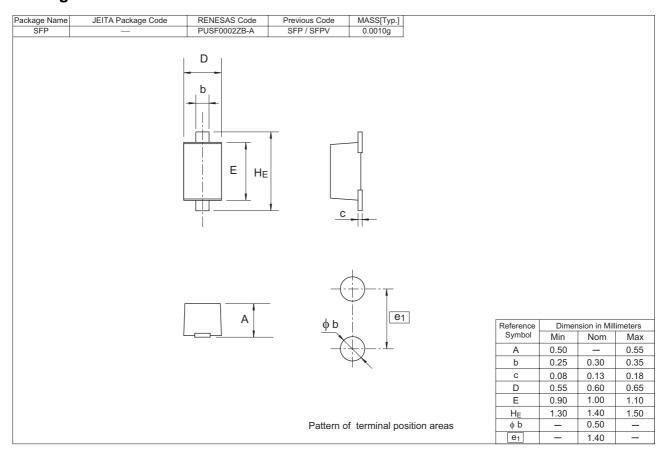
Notes: 1. Failure criterion;  $I_R \ge 20 \text{ nA}$  at  $V_R = 10 \text{ V}$ 

<sup>2.</sup> For SFP package, the material of lead is exposed for cutting plane. There for, soldering nature of lead tip part is considered as unquestioned. Please kindly consider soldering nature.

# **Main Characteristic**



# **Package Dimensions**



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